

SS34FL

Surface Mount Schottky Barrier Rectifier

Reverse Voltage - 40V Forward Current - 3.0A

FEATURES

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

MECHANICAL DATA

• Case: SMAF

• Terminals: Solderable per MIL-STD-750, Method 2026

• Approx. Weight:27mg 0.00086oz

Absolute Maximum Ratings and Electrical characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

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Parameter	Symbols	SS34FL					
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	40	V				
Maximum RMS voltage	V _{RMS}	28	V				
Maximum DC Blocking Voltage	V _{DC}	40	V				
Maximum Average Forward Rectified Current	I _{F(AV)}	3.0	А				
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	80	А				
Max Instantaneous Forward Voltage at 3 A	V _F	0.45	V				
Maximum DC Reverse Current T _a = 25°C at Rated DC Reverse Voltage T _a =100°C	IR	0.3 5	mA				
Typical Junction Capacitance 1)	Ci	450	pF				

Reja

 T_j

 T_{stg}

Typical Thermal Resistance 2)

Storage Temperature Range

Operating Junction Temperature Range

°C/W

°С

°С

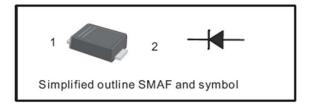
40

-55 ~ +125

-55 ~ +150

PINNING

PIN	DESCRIPTION				
1	Cathode				
2	Anode				



¹⁾ Measured at 1MHz and applied reverse voltage of 4 V D.C.

²⁾ P.C.B. mounted with 0.2 X 0.2" (5 X 5 mm) copper pad areas.





Fig.1 Forward Current Derating Curve

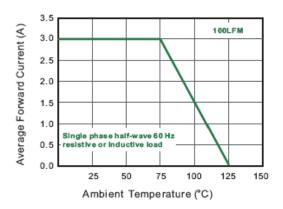


Fig.3 Typical Forward Characteristic

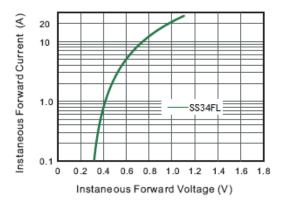


Fig.5 Maximum Non-Repetitive Peak Forward Surage Current

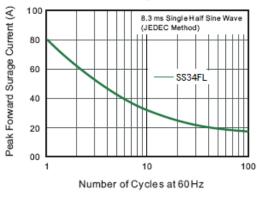


Fig.2 Typical Reverse Characteristics

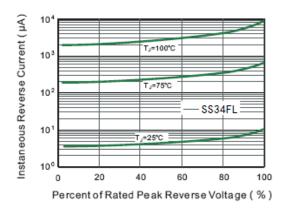


Fig.4 Typical Junction Capacitance

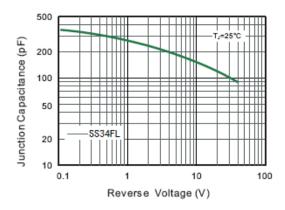
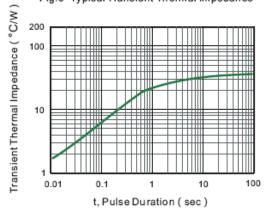


Fig.6- Typical Transient Thermal Impedance

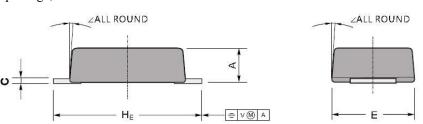


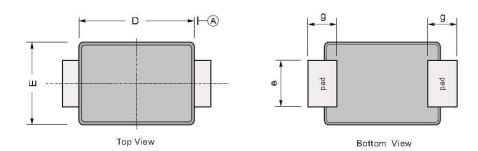
SMAF



PACKAGE OUTLINE

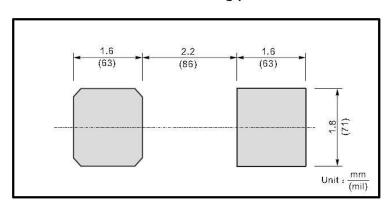
Plastic surface mounted package; 2 leads





UNIT		Α	С	D	Е	е	g	H∈	Z
mm	max	1.1	0.20	3.7	2.7	1.6	1.2	4.9	7°
	min	0.9	0.12	3.3	2.4	1.3	8.0	4.4	
mil	max	43	7.9	146	106	63	47	193	
	min	35	4.7	130	94	51	31	173	

The recommended mounting pad size



REV.08 3 of 3